



SOT1631-3

HQFN24, plastic, thermal enhanced quad flatpack; no leads;
24 terminals; 0.9 mm pitch; 12 mm x 12 mm x 2.1 mm body

25 January 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HQFN24
Package style descriptive code	HQFN (thermal enhanced quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	08-01-2016
Manufacturer package code	98ASA00426D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	12	-	mm
package width	-	12	-	mm
package height	-	2.1	-	mm
nominal pitch	-	0.9	-	mm
actual quantity of termination	-	24	-	



HQFN24, plastic, thermal enhanced quad flatpack; no leads; 24 terminals; 0.9 mm pitch; 12 mm x 12 mm x 2.1 mm body

2 Package outline

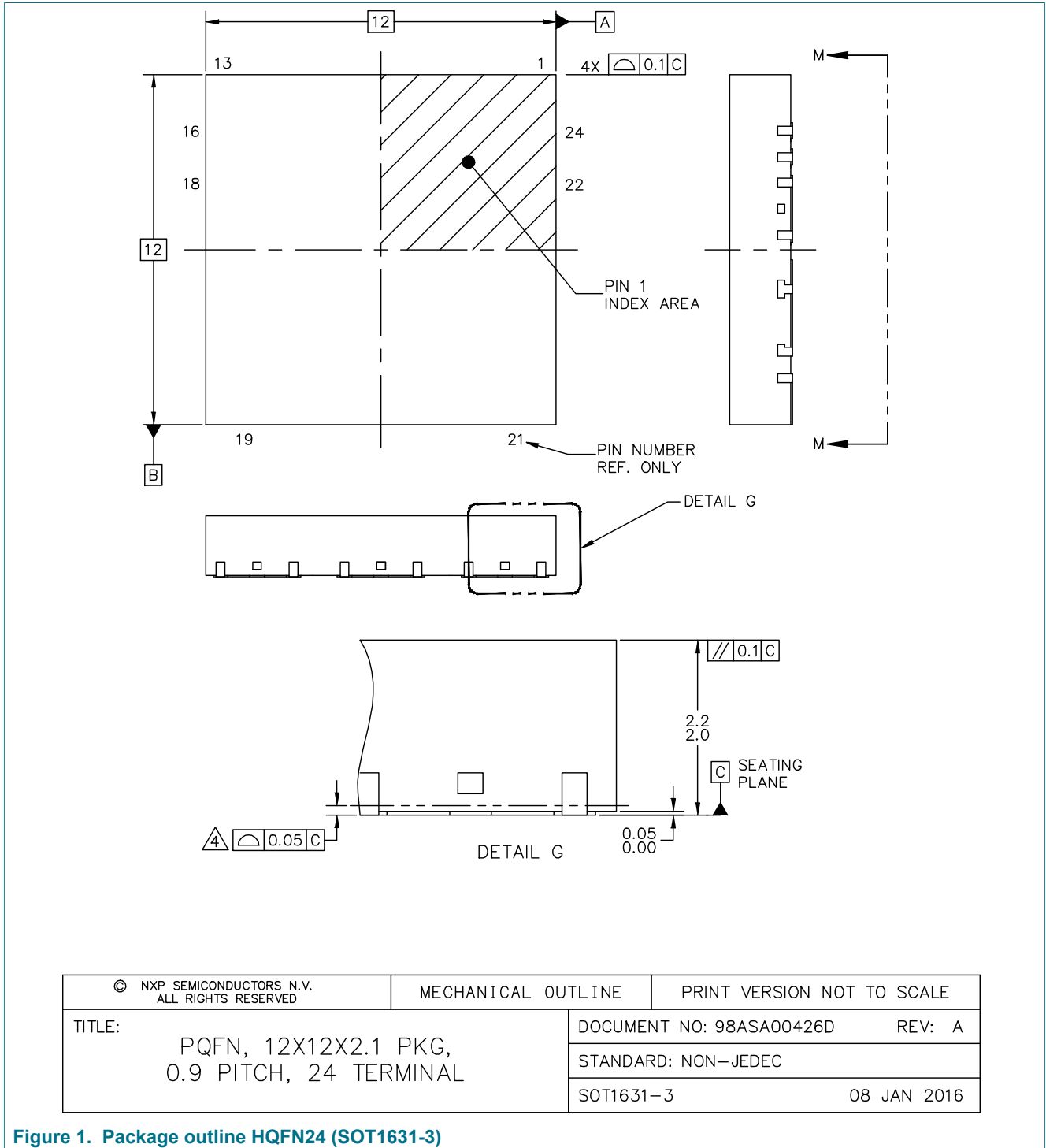


Figure 1. Package outline HQFN24 (SOT1631-3)

HQFN24, plastic, thermal enhanced quad flatpack; no leads; 24 terminals; 0.9 mm pitch; 12 mm x 12 mm x 2.1 mm body

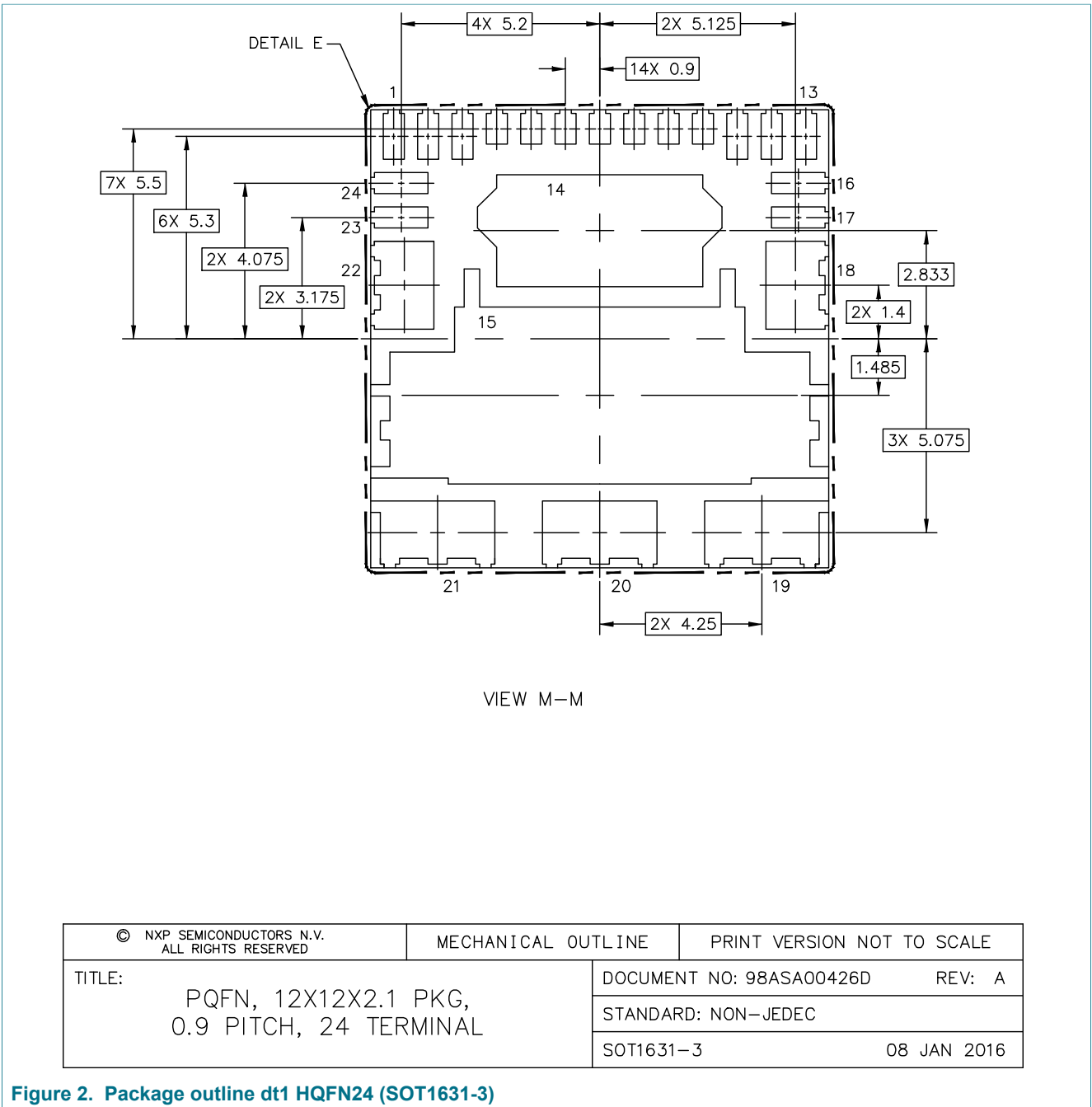


Figure 2. Package outline dt1 HQFN24 (SOT1631-3)

HQFN24, plastic, thermal enhanced quad flatpack; no leads; 24 terminals; 0.9 mm pitch; 12 mm x 12 mm x 2.1 mm body

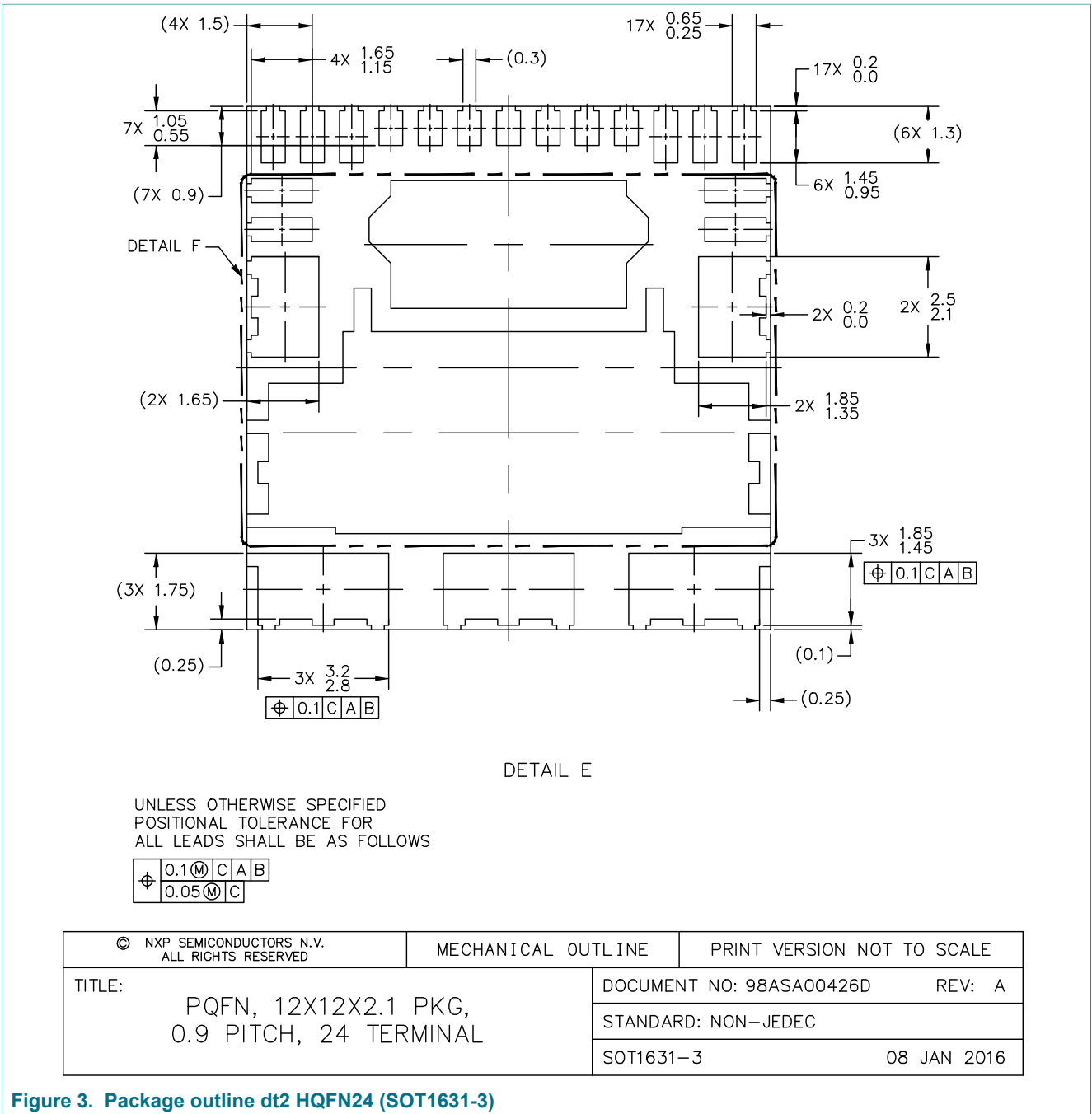
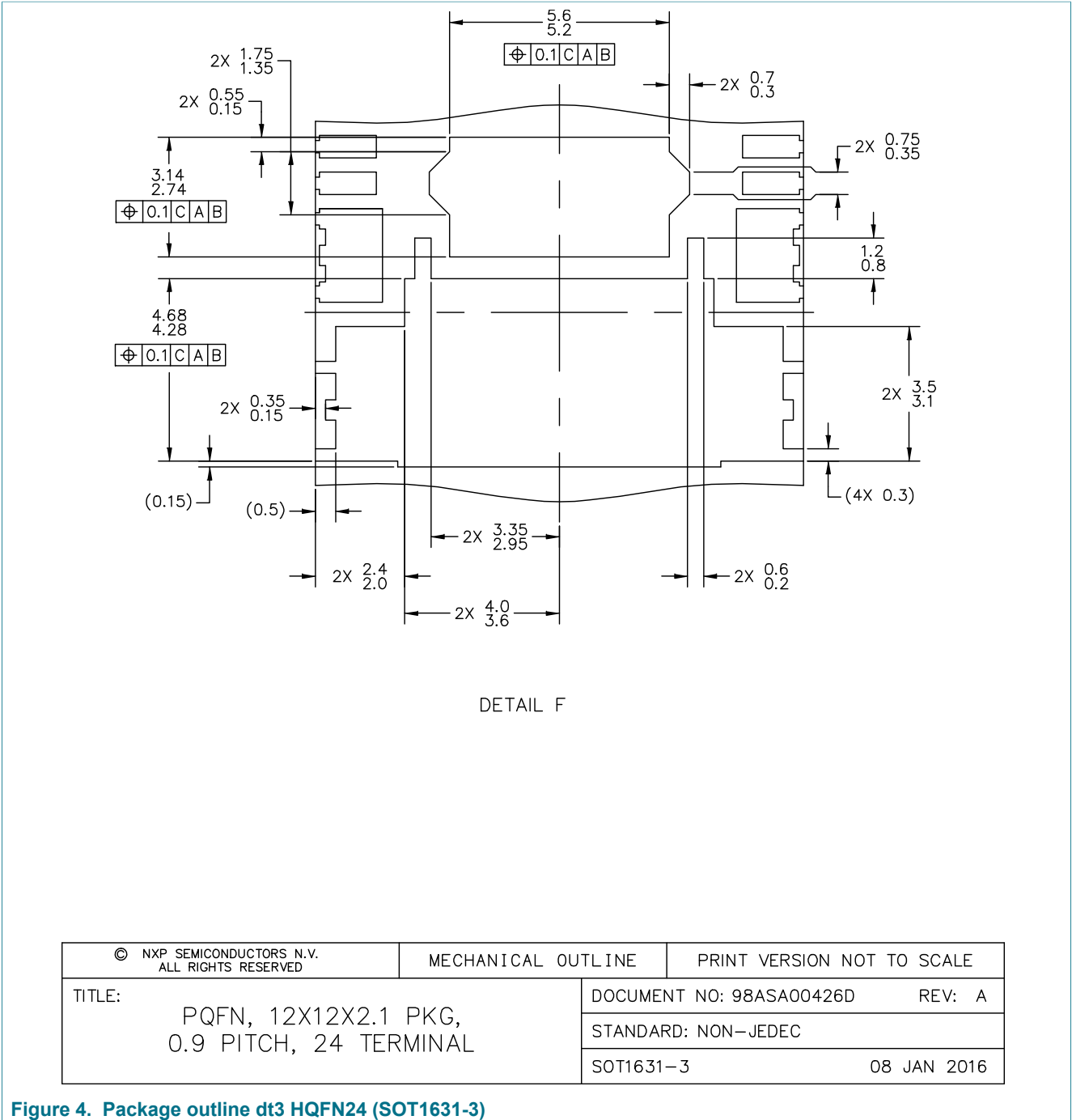



Figure 3. Package outline dt2 HQFN24 (SOT1631-3)

HQFN24, plastic, thermal enhanced quad flatpack; no leads; 24 terminals; 0.9 mm pitch; 12 mm x 12 mm x 2.1 mm body



HQFN24, plastic, thermal enhanced quad flatpack; no leads; 24 terminals; 0.9 mm pitch; 12 mm x 12 mm x 2.1 mm body

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS NON-JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS AND CORNER LEADS.
5. MINIMUM METAL GAP IS GUARANTEED TO BE 0.25 MM.

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TITLE: PQFN, 12X12X2.1 PKG, 0.9 PITCH, 24 TERMINAL	DOCUMENT NO: 98ASA00426D	REV: A
	STANDARD: NON-JEDEC	
	SOT1631-3	08 JAN 2016

Figure 5. Package outline note HQFN24 (SOT1631-3)

3 Legal information

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